



TRIPLE BI-DIRECTIONAL TVS ARRAY FOR ESD PROTECTION

This Triple Bi-directional TVS/Zener Array family have been designed to protect sensitive equipment against ESD in CMOS circuitry operatin at 5V. This TVS array offers an integrated solution to protect up to 3 data lines in applications, where the board space is a premium, in a Quad Flat no-Lead package that only occupies an area of 1.8 sq mm.

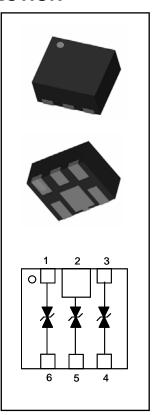
SPECIFICATION FEATURES

- IEC61000-4-2 ESD 20kV air, 15kV Contact Compliance
- Low Leakage Current, Maximum of 1µA at rated voltage
- Maximum Capacitance of 18pF per device at 0Vdc 1MHz
- Peak Power Dissipation of 50W 8/20µs Waveform
- Quad Flat No Lead package QFN (1.2x1.5 sg mm, Height: 0.75mm)
- Lead Free Package 100% Tin Plating, Matte finish

APPLICATIONS

- Personal Digital Assistant (PDA)
- Digital Cameras
- Portable Instrumentation
- Mobile Phones and Accessories
- MP3 Players





MAXIMUM RATINGS (Per Device)

Rating	Symbol	Value	Units
Peak Pulse Power (8/20µs Waveform)	P _{PP}	50	W
Peak Pulse Current (8/20µs Waveform)	I _{PPM}	5	А
ESD Voltage (HBM Per MIL STD883C - Method 3015-6)	V _{ESD}	25	kV
Operating Temperature Range	TJ	-55 to +150	°C
Storage Temperature Range	T _{stg}	-55 to +150	°C

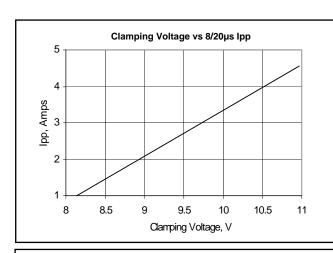
ELECTRICAL CHARACTERISTICS (Per Device) Tj = 25°C

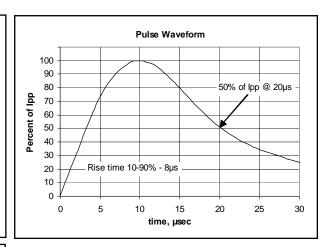
Parameter	Symbol	Conditions	Min	Typical	Max	Units
Reverse Stand-Off Voltage	V_{WRM}				5	V
Reverse Breakdown Voltage	V_{BR}	I _{BR} =1mA	6			V
Reverse Leakage Current	I _R	V _R =5V			1	μΑ
Clamping Voltage (8/20µs)	V _c	Ipp =4A			11	V
Off State Junction Capacitance	Cj	0 Vdc Bias f = 1MHz		15.5	18	pF

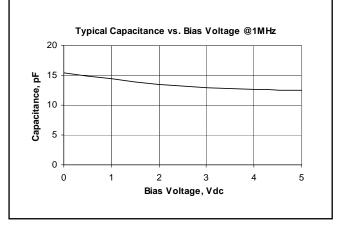




TYPICAL CHARACTERISTIC CURVES (Per Device) Tj = 25°C



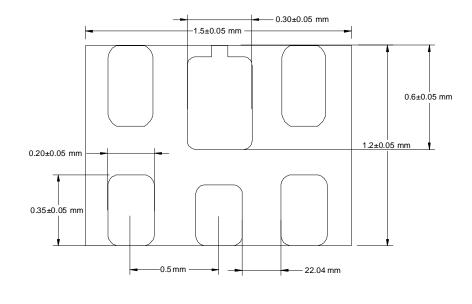


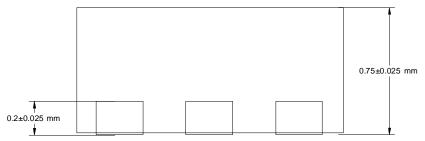


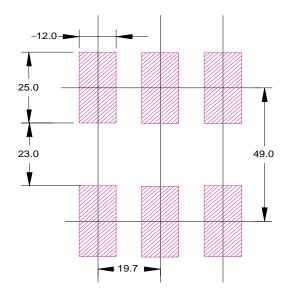




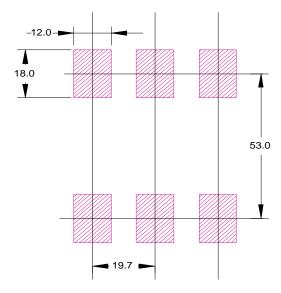
PACKAGE DIMENSIONS AND SUGGESTED PAD LAYOUT







Suggested Pad Layout (in mils)



Alternate Pad Layout SOT666 (in mils)